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SEMICONDUCTOR DEVICE

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[There are no amendments to this patent.]

Claims

1. A semiconductor characterized by the fact that it includes first and second semiconductor chips, in which bonding pads to and from which the same signal is input and/output are arranged at specular symmetric positions, and several inner leads, which are sandwiched between the first and second semiconductor chips and respectively connected to each pair of bonding pads to and from which the above-mentioned same signal of both semiconductor chips is input and/or output.

2. The semiconductor of Claim 1, characterized by the fact that bonding pads, to which chip selecting signals of the above-mentioned first and second semiconductor chips are input, are respectively not arranged at specular symmetric positions.

3. The semiconductor of Claim 1, characterized by the fact that bonding pads, to and from which data input and output signals of the above-mentioned first and second semiconductor chips are input and output, are respectively not arranged at specular symmetric positions.

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